

2017 CMPUG SPRING MEETING – FINAL AGENDA

Topic: Advances in CMP Consumables, Materials and Tools

Meeting Date: April 13, 2017

Time: 12:00 pm - 6:00 pm

Location: Embassy Suites Downtown Portland
319 SW Pine Street
Portland, Oregon 97204

Parking: Located at the hotel or nearby parking structures

FREE CONFERENCE REGISTRATION

Click for [Online Registration](#)

Speakers/Agenda listed below

Chair (Co-Chair):

Michael Pevny, 3M, mpevny@mmm.com

Jeff McKinnis, Fujimi, jmckinnis@fujimico.com

The Chemical Mechanical Planarization Users Group (CMPUG) Symposium on Advances in CMP Consumables, Materials and Tools commences on **April 13, 2017**. The symposium will provide an international forum for academic researchers, industrial practitioners and engineers from around the world for the exchange of information on state-of-the-art research in CMP semiconductor technology. The CMPUG promotes the exchange of opportunities, ideas, friendly relationships and research collaboration. The areas of focus for this meeting will be the following:

- [CMP consumables and materials](#)
- [CMP Polishing and Metrology Tools](#)
- [CMP Process Integration](#)

SPEAKERS/AGENDA

12:30 pm – Registration/Badge Pick up at entrance to Queen Marie Ballroom inside the Embassy Suites

12:50 pm – Welcome and Acknowledgment of sponsors; by conf co-chairs Michael Pevny (3M) and Jeff McKinnis (Fujimi)

1:00 pm – High Rate Acidic Slurries, Julia Kozhukh, Dow

1:25 pm – Holographic Characterization of Agglomerates, Fook Cheong, Spheryx

1:50 pm – Stribeck Curve Improvements for Cu and WCMP on Soft Pads, Ara Philipossian, University of Arizona and Araca Inc.

2:20 pm – Enhanced Material Removal Rate for III/V Semiconductors, Bahar Basim, and Sebnem Ozbek, Ozyegin University

2:45 pm – Awards/Recognition; Dr. Babu

2:55 pm – Coffee Break/Poster Session/Networking

3:30 pm – CMP of Divinylsiloxane-bis-benzocyclobutene (DVS-BCB or BCB) low-k ILD Polymer, Zenon Carlos, Hughes Research Labs.

3:55 pm –Bulk Cu CMP: Development and challenges of high removal rate, low topography slurries, James McDonough, Fujifilm Planar Solutions LLC

4:20 pm –High Performance Pad Conditioning (HPPC) Arm for Advanced Pad Conditioning, Raghava Kakireddy, Applied Materials

4:45 pm – The Impact of Sample Containers on Large Particle Count for CMP slurries, Brian Kim, Fujimi Corporation

5:10 pm – ICPT Announcement

5:15 pm – Concluding remarks by conf co-chairs Michael Pevny (3M) and Jeff McKinnis (Fujimi)

5:20 pm – Hors d'oeuvre served with cash bar

6:00 pm – Meeting adjourn

All presentations will be posted on the CMPUG Proceedings webpage following the meeting.

If you would like to sponsor this meeting or list a banner ad on the User Group website, please check out our "NCCA VS Marketing/ Sponsorship" opportunities at: [NCCA VS marketing opportunities](#)